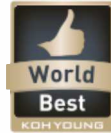


Art of 3D Technology

Uncompromising and leading solutions



KY8030-2

World - Best Seller Full 3D Solder Paste Inspection

- ✔ The best-selling standard 3D SPI in the world
- ✔ The strongest printing process optimization tool
- ✔ The world's best measurement accuracy and reliability



User-friendly Software



3D Data based
SMT Process Control
System

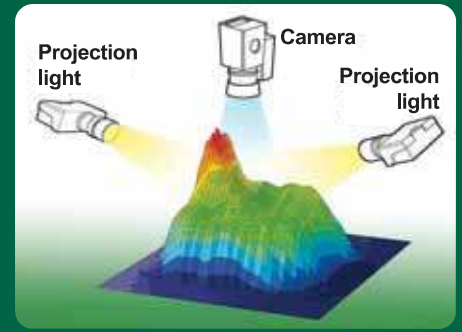


Real Time Warp
Compensation



KY8030-2

World-Best Seller Full 3D Solder Paste Inspection



↗ Dual Projection Technology

KY8030-2 delivers true 3D inspection without concern for inaccuracies resulting from shadowing.

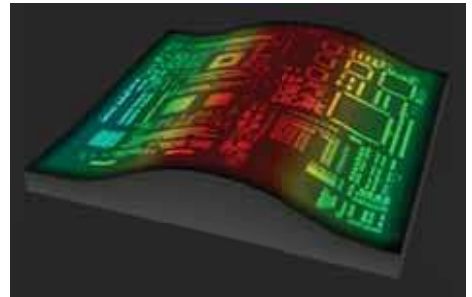


Optional

○ Z-tracking 3D Compensation Solution

- Koh Young's **Multi-Frequency Moiré Technology** applied *Patented
- Real time measurement and compensation of board warp, with respect to the ideal plane
- Real time online provision of high quality PCB images with measurement data

PCB Warp 3D Display

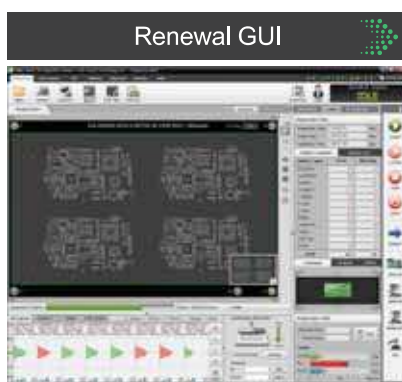


Before Warp Compensation

After Warp Compensation



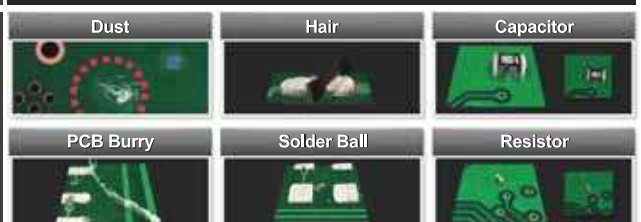
- Optimized display for the user with smart menu groupings
- Supports user's defect readability and system usability by more intuitive software
- Detects a wide range of defects using real images and 3D data



Real Color 3D Image
Optional

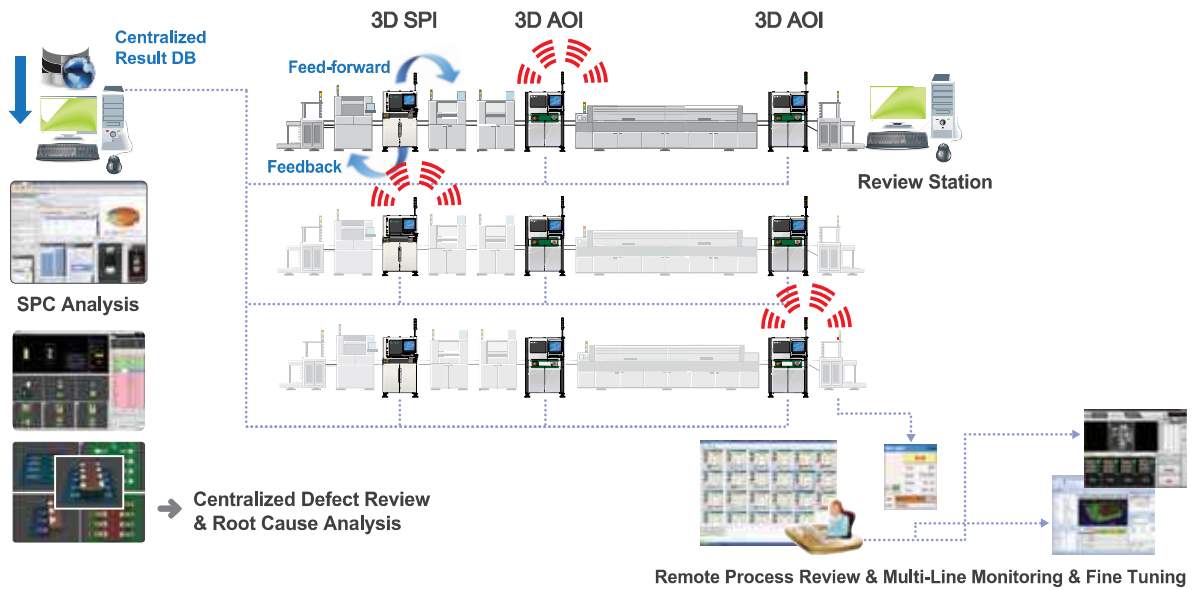


Foreign Material Inspection
Optional



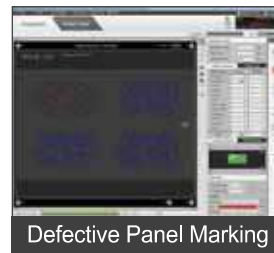
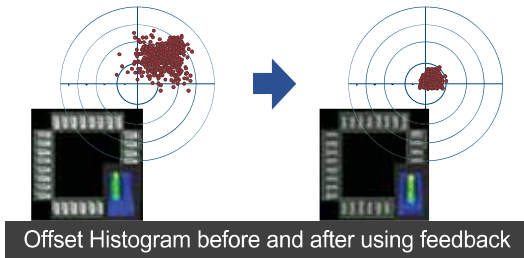


Koh Young's KSMART Solution



Closed Loop Real Time Screen Printer Communication

Optional

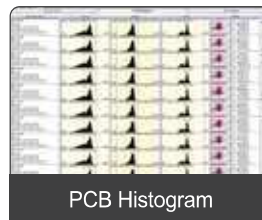


- Real time communication of printing process monitoring data with screen printers
- Result reporting after optimization by Koh Young's SPC software
- Real time communication of pick-and-place process monitoring data with mounters
- Supports process optimization by controlling panels containing defects



SPC Plus Printing Process Optimization Tool

- Review, diagnosis and optimization of printing, pick-and-place and reflow processes
- 3D data based SPI-AOI communication solution
- Traces root cause of defects by storing and communicating inspection results from Koh Young's 3D SPI and 3D AOI Systems



KSMART Link Communication Solution



- Provides intuitive statistical process analysis data by using reliable 3D measurement data
- Communicates with a wide range of production management systems

Must-check Requirements of 3D SPI System



Requirements	Solutions																
Solution to Shadow Problem	• 3D Shadow Free Moiré Technology & Dual Projection																
Real Time PCB Warp Compensation (2D+3D Solution)	• Warp Compensation																
Operator User-friendliness	• Renewal GUI, Real Color 3D Image																
Foreign Material Inspection	• 3D Foreign Material Inspection (optional)																
Inspection Items	<ul style="list-style-type: none"> • Volume, Area, Height, Offset, Bridging, Shape Deformity, Coplanarity • Insufficient/Excessive/Missing Paste, Bridging, Shape Deformity, Paste Offset, Coplanarity 																
Inspection Performance	<table border="1"> <thead> <tr> <th></th> <th>15µm</th> <th>20µm</th> <th>25µm</th> </tr> </thead> <tbody> <tr> <td>FOV Size</td> <td>30×30mm(1.18×1.18 inch)</td> <td>40×40mm(1.57×1.57 inch)</td> <td>50×50mm(1.97×1.97 inch)</td> </tr> <tr> <td>Full 3D Inspection Speed</td> <td colspan="3">22.5~56.1 cm²/sec (Inspection speed varies by PCB and inspection condition.)</td> </tr> <tr> <td>Min. Distance between Paste Deposit</td> <td>100µm (3.94 mils)</td> <td>150µm (5.91 mils)</td> <td>200µm (7.87 mils)</td> </tr> </tbody> </table> <ul style="list-style-type: none"> • 4M Pixel Camera • IR-RGB LED Dome Styled Illumination • 0.37µm • 1µm • 2.5 nano meter (PZT Accuracy) • < 10% at 6σ • 10×10mm 0.39×0.39 inch • 400µm (2mm optional) 15.75 mils (78.74 mils optional) • 100µm (150µm paste height) 3.94 mils (5.91 mils paste height) • Possible 		15µm	20µm	25µm	FOV Size	30×30mm(1.18×1.18 inch)	40×40mm(1.57×1.57 inch)	50×50mm(1.97×1.97 inch)	Full 3D Inspection Speed	22.5~56.1 cm ² /sec (Inspection speed varies by PCB and inspection condition.)			Min. Distance between Paste Deposit	100µm (3.94 mils)	150µm (5.91 mils)	200µm (7.87 mils)
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Min. Distance between Paste Deposit	100µm (3.94 mils)	150µm (5.91 mils)	200µm (7.87 mils)														
PCB Handling	<ul style="list-style-type: none"> • Automatic • Front / Rear Fixed (factory setting) 																
Software	<ul style="list-style-type: none"> • Supported Input Format • Programming S/W • Statistical Process Control Tool • Operator User-friendliness • Operating System 																
Add-on Solutions	<ul style="list-style-type: none"> • 1D & 2D Handy Barcode Reader • 1D & 2D Inline Barcode Reader • Offline Programming Station • Offline SPC Plus Station • Standard Calibration Target • UPS 																

※ Above specifications are subject to change without notice.

	M	L	DL	XL
Max. PCB Size	330X330mm (13X13 inch)	510X510mm (20X20 inch)	Dual: 510X320mm (20X12.6 inch) Single: 510X580mm (20X22.8 inch)	850X690mm (33.4X27.1 inch)
Min. PCB Size	50X50mm (1.97X1.97 inch)			70X70mm (2.7X2.7 inch)
PCB Thickness	0.4~5mm (0.015~0.20 inch)			0.5~8mm (0.02~0.31 inch)
Max. PCB Weight	Standard: 2kg, Heavy Weight Option: 5kg			
Machine Weight	550Kg(1212 lbs)	600Kg(1322 lbs)	700Kg(1543 lbs)	850Kg(1874 lbs)
Bottom Side Clearance	50mm(1.97 inch)			
Supplies	200~240VAC, 50/60Hz Single Phase, 5Kgf/cm ²			
W	820mm(32.2 inch)	1000mm(39.3 inch)		1350mm(53.1 inch)
D	1265mm(49.8 inch)	1265mm(49.8 inch)	1445mm(56.9 inch)	1445mm(56.9 inch)
H	1627mm(64 inch)			
F	985mm(38.7 inch)		1165mm(45.8 inch)	

